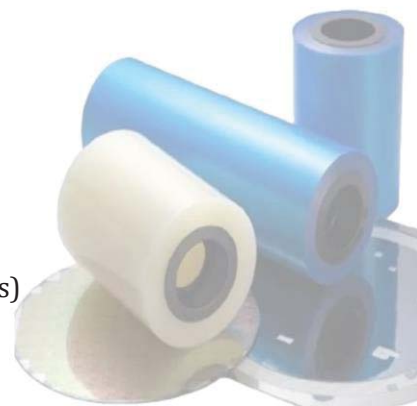


NEXTECK UV Dicing Tape

High-performance adhesive tape for semiconductor and wafer processing

Features

- Wide range of items available with adhesive thicknesses (5μm~)
- Prevents die-fly and chipping (cracking) on the backside surface
- Easy pickup (easy to peel)
- Exhibits superior adhesive qualities for workpieces that are incredibly anti-adhesive, such as those made from EMC (epoxy molding compounds)
- Anti-static types are available (optional)



Selected Specifications

P/N	Base Film	Color	Total Thickness (μm)	Adhesive Thickness (μm)	Adhesive Strength (after UV irradiation) N/20mm	Features
NDT-CJ80	PVC	Transparent	80	10	2.64(0.10)	Exhibits excellent pickup
NDT-CJ100			100		2.3(0.18)	
NDT-SPMC0805	PO	Milk White	83	5	3.41(0.11)	Limits the amount of chipping and cracks on the backside surface
NDT-SPM60805			85		9.8(0.14)	
NDT-SPM31005			105		4.39(0.10)	
NDT-SPAT1005			105		1.97(0.06)	
NDT-SPAT110			110	10	2.58(0.05)	Exhibits excellent pickup
NDT-SPBZ110			110		2.83(0.05)	
NDT-SPM3110			110		6.54(0.09)	Compatible with small-sized chips
NDT-SPM31025			125	25	11.05(0.09)	Compatible with workpieces that are incredibly anti-adhesive
NDT-SPM31510			160	10	5.86(0.10)	
NDT-SPM31525			175	25	11.49(0.09)	
NDT-PM31410			150	10	12.6(0.10)	
NDT-PM31420			160	20	15.5(0.10)	
NDT-PM41410			150	10	16.9(0.10)	
NDT-PM41420			160	20	20.4(0.10)	
NDT-TM31005	PET	Transparent	105	5	7.09(0.03)	Limits the amount of chipping and cracks on the backside surface
NDT-TM31025			125	25	21.39(0.05)	
NDT-TMC1025			125		28.18(0.05)	
NDT-TSG1025			125		35.04(0.16)	
NDT-TMC1915			203	15	19.83(0.04)	

Recommended Applications

- Semiconductor wafer dicing
- Small die pickup
- Glass and crystal processing
- Attachment to anti-adhesive components like EMC packages